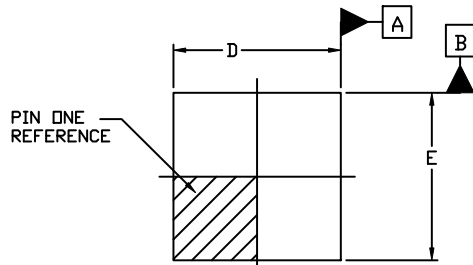


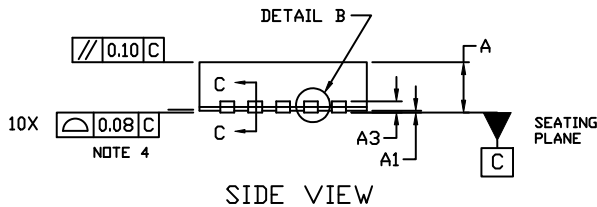


DFNW10 3x3, 0.5P
CASE 507AM
ISSUE A

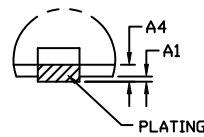
DATE 12 JUN 2018



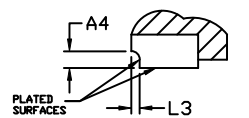
TOP VIEW



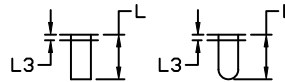
SIDE VIEW



DETAIL B

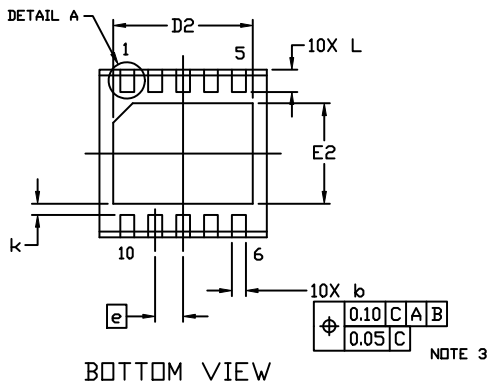


SECTION C-C



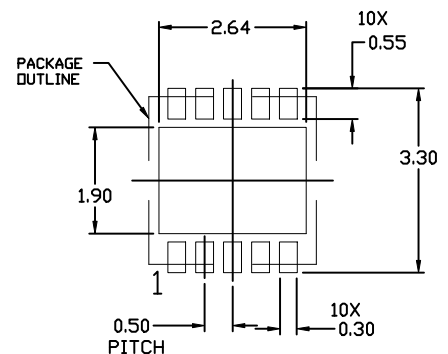
ALTERNATE CONSTRUCTION

DETAIL A



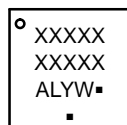
BOTTOM VIEW

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.80	0.90	1.00
A1	0.00	---	0.05
A3	0.20 REF		
A4	0.10	---	---
b	0.20	0.25	0.30
D	2.85	3.00	3.15
D2	2.40	2.50	2.60
E	2.85	3.00	3.15
E2	1.70	1.80	1.90
e	0.50 BSC		
k	0.19 REF		
L	0.35	0.40	0.45
L3	---	0.05	0.10



RECOMMENDED MOUNTING FOOTPRINT

GENERIC MARKING DIAGRAM*



- XXXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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